8.890 SEE NOTES PADS BSC 11.250 2.72 - 2.92 · HX Y $\sqrt{1}$ SEE NOTES BSC - 0.605 - 0.665 3 5 1 0.605 - 0.665 4 MOLD SUBSTRATE CAP 5.080 6.250 3 BSC BSC ← 0.27 - 0.37 -> ۲ 2.40 - 2.602 1.270 Ζ C bbb Z BSC DETAIL A 1 PAD 1-🕈 🗀 aaa Z CORNER PAD 1 C (0.30) 4PACKAGE TOP VIEW Н G F D С В А Е DETAIL A PACKAGE BOTTOM VIEW PACKAGE SIDE VIEW 0.0000 4.445 3.175 0.635 0.635 1.905 1.905 3.175 4.445 NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994 2. ALL DIMENSIONS ARE IN MILLIMETERS 2.540 3 LAND DESIGNATION PER JESD MO-222, SPP-010 AND SPP-020 4 DETAILS OF PAD #1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. 1.270 THE PAD #1 IDENTIFIER MAY BE EITHER A MOLD OR A MARKED FEATURE **1**1 0.0000 -5. PRIMARY DATUM -Z- IS SEATING PLANE **T**LINEAR 0.9525 1.270 1.5875 6. THE TOTAL NUMBER OF PADS: 35 LTMXXXXXX $\overline{7}$ PACKAGE ROW AND COLUMN LABELING MAY VARY µModule ·<u>Z!</u>\ AMONG µModule PRODUCTS. REVIEW EACH PACKAGE 2.540 LAYOUT CAREFULLY COMPONENT PIN "A1" 101 TOLERANCE SYMBOL 0.9525 - 0.635 - 0.635 - 0.3175 -TRAY PIN 1 0.15 aaa BEVEL bbb 0.10 SUGGESTED PCB LAYOUT PACKAGE IN TRAY LOADING ORIENTATION TOP VIEW LGA 35 0113 REV B

LGA Package 35-Lead (11.25mm × 6.25mm × 2.82mm) (Reference LTC DWG # 05-08-1805 Rev B)